



Material Content Data Sheet



Sales Product Name		BTS5210L		Issued		31. July 2018			
MA#		MA002843724							
Package		PG-DSO-12-9		Weight*		366.68 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.505	0.96	0.96	9558	9558	
leadframe	inorganic material	phosphorus	7723-14-0	0.061	0.02		167		
	non noble metal	iron	7439-89-6	0.204	0.06		557		
	non noble metal	copper	7440-50-8	203.829	55.58	55.66	555886	556610	
	non noble metal	aluminium	7429-90-5	0.735	0.20	0.20	2005	2005	
wire	non noble metal	aluminium	7429-90-5	0.735	0.20	0.20	2005	2005	
encapsulation	organic material	carbon black	1333-86-4	0.303	0.08		825		
	plastics	epoxy resin	-	21.629	5.90		58987		
	inorganic material	silicondioxide	60676-86-0	129.321	35.27	41.25	352685	412497	
leadfinish	non noble metal	tin	7440-31-5	3.310	0.90	0.90	9026	9026	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		4		
	non noble metal	nickel	7440-02-0	0.617	0.17	0.17	1683	1687	
solder	non noble metal	tin	7440-31-5	0.063	0.02		172		
	noble metal	silver	7440-22-4	0.079	0.02		215		
	non noble metal	lead	7439-92-1	3.018	0.82	0.86	8230	8617	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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